

General Description

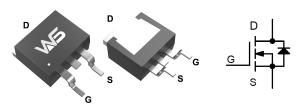
The WSK96N08 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

Product Summery

BVDSS	RDSON	ID
80V	7mΩ	96A

The WSK96N08 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO-263-2L Pin Configuration



Applications

- Switching application
- Power management for inverter systems

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	±25	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	90	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	64	А
I _{DM}	Pulsed Drain Current ²	360**	Α
EAS	Single Pulse Avalanche Energy ³	416***	mJ
I _{AS}	Avalanche Current	200	Α
P _D @T _C =25°C	Total Power Dissipation ³	185	W
P _D @T _C =100°C	Total Power Dissipation ³	92	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C

Note: * Repetitive rating; pulse width limited by max.junction temperature.

- ** Surface mounted on 1in2 FR-4 board.
- *** Limited by TJmax , starting TJ=25 $^{\circ}$, L = 0.5mH, RG= 25 Ω , VGS =10V.



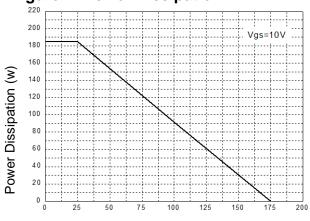
Electrical Characteristics (T $_{J}$ =25 $\,$ \subset , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.0		V/°C	
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =45A		7	9	mΩ	
R _{DS(ON)}		V_{GS} =6V , I_D =10A		10	12	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V V I 0504	2	3	4	٧	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-6.57		mV/℃	
	Drain Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25℃		-	1	uA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃		-	2		
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, V_{DS} =0V		-	±100	nA	
gfs	orward Transconductance	V _{DS} =5V , I _D =20A	18			S	
Qg	Total Gate Charge (10V)			86			
Q _{gs}	Gate-Source Charge	V _{DS} =50V , V _{GS} =10V , I _D =120A		16		nC	
Q_{gd}	Gate-Drain Charge			28			
T _{d(on)}	Turn-On Delay Time			25			
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V ,		42			
T _{d(off)}	Turn-Off Delay Time	$R_G=6\Omega I_D=145A$,		62		ns	
T _f	Fall Time	RL=30Ω		19			
C _{iss}	Input Capacitance			3800			
Coss	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		389		pF	
C _{rss}	Reverse Transfer Capacitance			250			
VsD	Diode Forward Voltage	I _{SD} =45A,V _{GS} =0V		0.8		V	
trr	Reverse Recovery Time	1 -45A dl /dt-400A/:		60		ns	
Qrr	Reverse Recovery Charge	IsD=45A,dIsD/dt=100A/μs		125		nC	

Note: *Pulse test, pulse width ≤ 300 us, duty cycle $\leq 2\%$

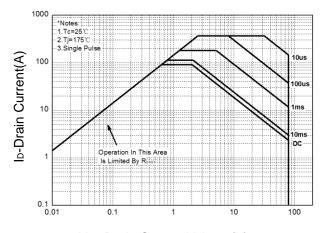
Typical Operating Characteristics

Figure 1: Power Dissipation



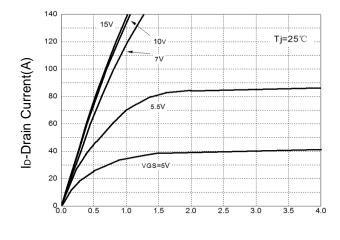
Tc-Case Temperature($^{\circ}$ C)

Figure 3: Safe Operation Area



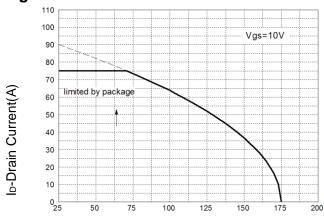
V_{DS}-Drain-Source Voltage(V)

Figure 5: Output Characteristics



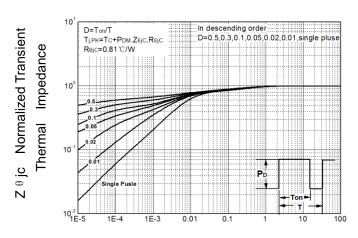
V_{DS}-Drain-Source Voltage (V)

Figure 2: Drain Current



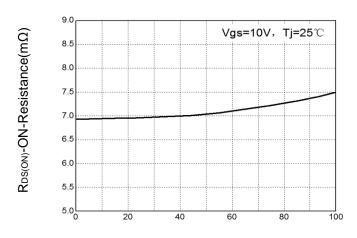
Tc-Case Temperature(°C)

Figure 4: Thermal Transient Impedance



Maximum Effective Transient Thermal Impedance, Junction-to-Case

Figure 6: Drain-Source On Resistance

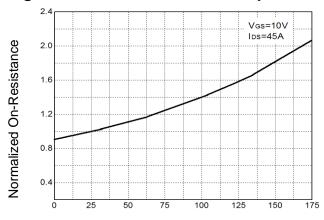


ID-Drain Current(A)



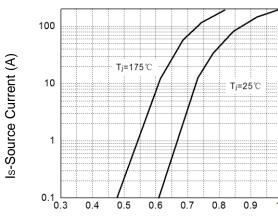
Typical Operating Characteristics

Figure 7: On-Resistance vs. Temperature



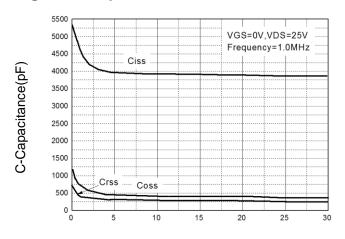
Tj-Junction Temperature (°C)

Figure 8: Source-Drain Diode Forward



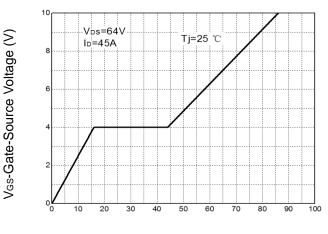
Vsp-Source-Drain Voltage(V)

Figure 9: Capacitance Characteristics



V_{DS}-Drain-Source Voltage (V)

Figure 10: Gate Charge Characteristics



QG-Gate Charge (nC)

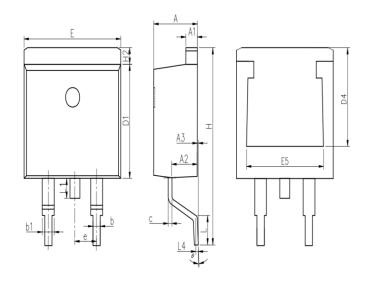


Device Per Unit

Package Type	Unit	Quantity
TO-263-2L	Reel	50

Package Information

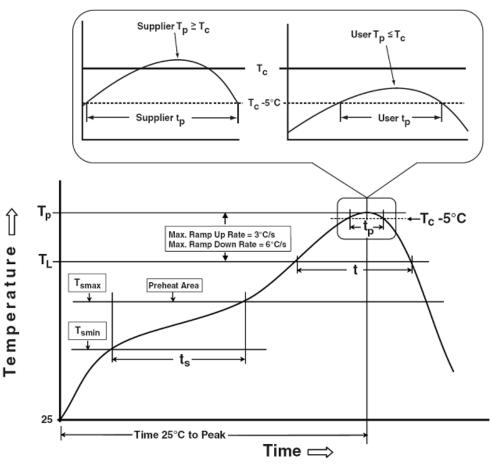
TO-263-2L



COMMON DIMENSIONS

SYMBOL	mm			
STIVIBUL	MIN	NOM	MAX	
А	4.37	4.57	4.77	
A1	1.22	1.27	1.42	
A2	2.49	2.69	2.89	
A3	0	0.13	0.25	
b	0.7	0.81	0.96	
b1	1.17	1.27	1.47	
С	0.3	0.38	0.53	
D1	8.5	8.7	8.9	
D4	6.6	-	-	
E	9.86	10.16	10.36	
E5	7.06	-	-	
е	2.54 BSC			
Н	14.7	15.1	15.5	
H2	1.07	1.27	1.47	
L	2	2.3	2.6	
L1	1.4	1.55	1.7	
L4	0.25 BSC			
θ	0°	5°	9°	

Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
Preheat & Soak Temperature min (T _{smin}) Temperature max (T _{smax}) Time (Tsmin to Tsmax) (t _s)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds	
Average ramp-up rate (T _{smax} to T _P)	3 °C/second max.	3°C/second max.	
Liquidous temperature (T _L) Time at liquidous (t _L)	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body Temperature (T _P)*	See Classification Temp in table 1	SeeClassification Tempin table 2	
Time (t _P)** within 5°C of the specified classification temperature (T _c)	20** seconds	30** seconds	
Average ramp-down rate (Tpto Tsmax)	6 °C/second max.	6 °C/second max.	
Time 25°C to peak temperature	6 minutes max.	8 minutes max.	
*Tolerance for neak profile Temperature (T _o) is defined as a supplier minimum and a user maximum			

^{*}Tolerance for peak profile Temperature (T_P) is defined as a supplier minimum and a user maximum.

^{**} Tolerance for time at peak profile temperature (t₂) is defined as a supplier minimum and a user maximum.



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